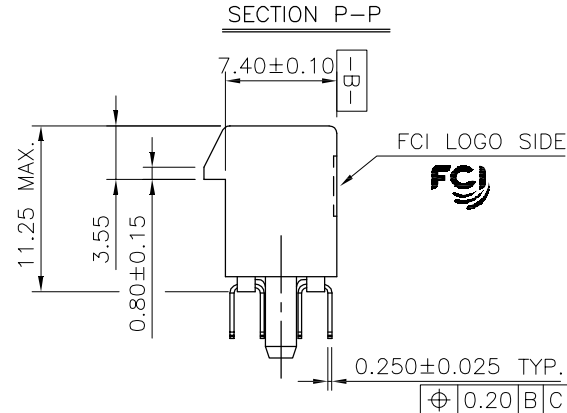
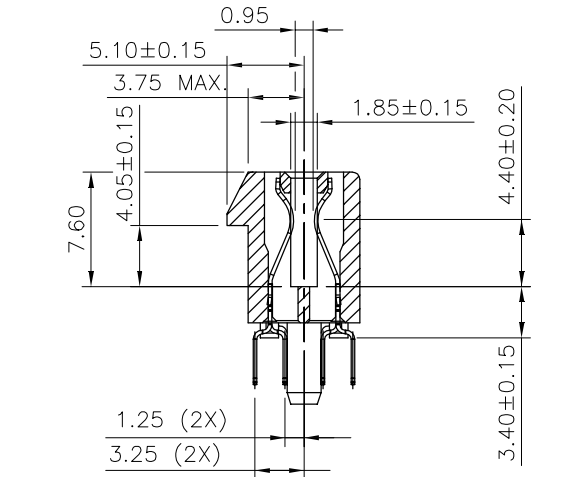
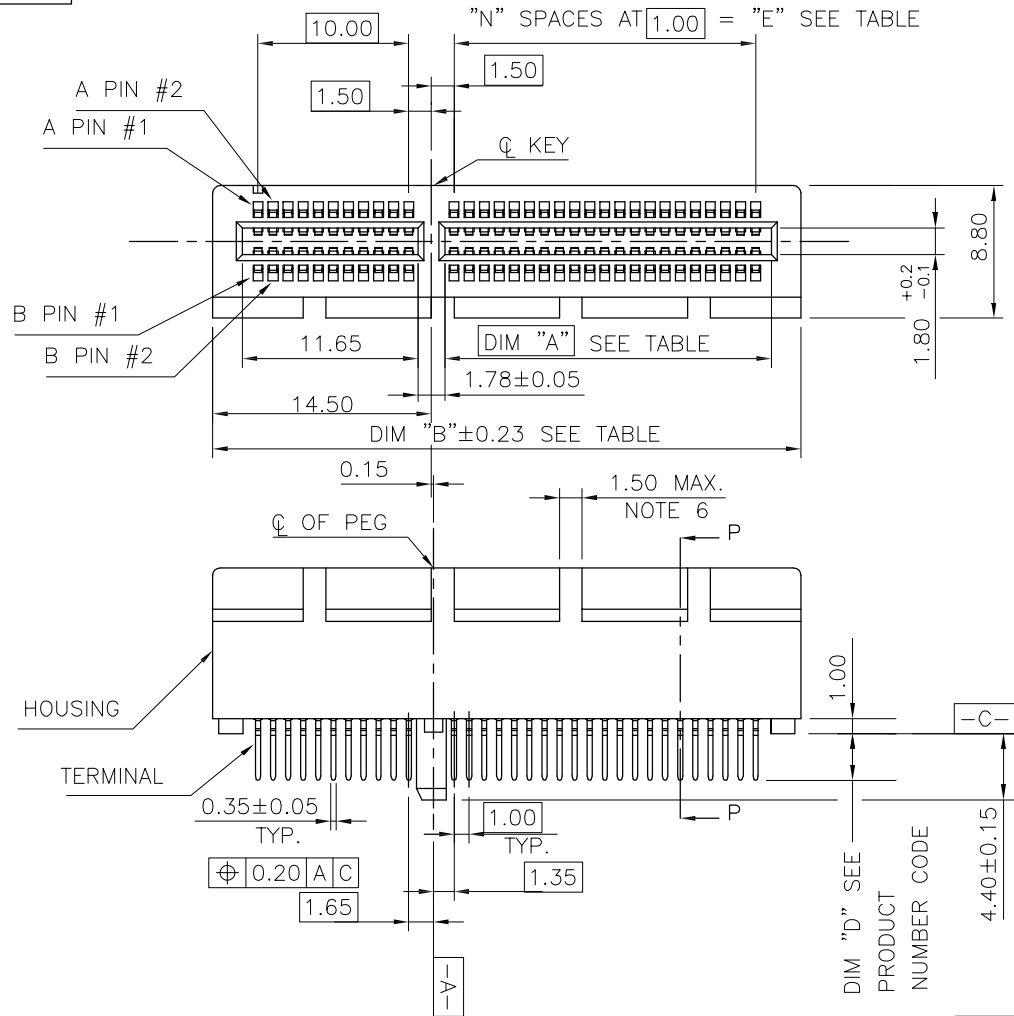


PRODUCT NO.
10108777-X2XXXX



SINGLE PLASTIC PEG TYPE

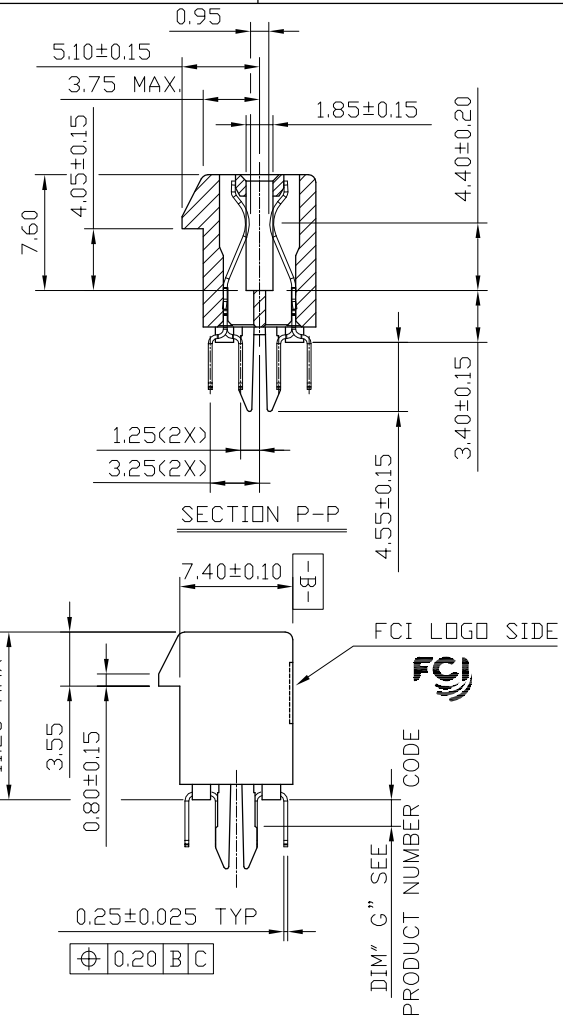
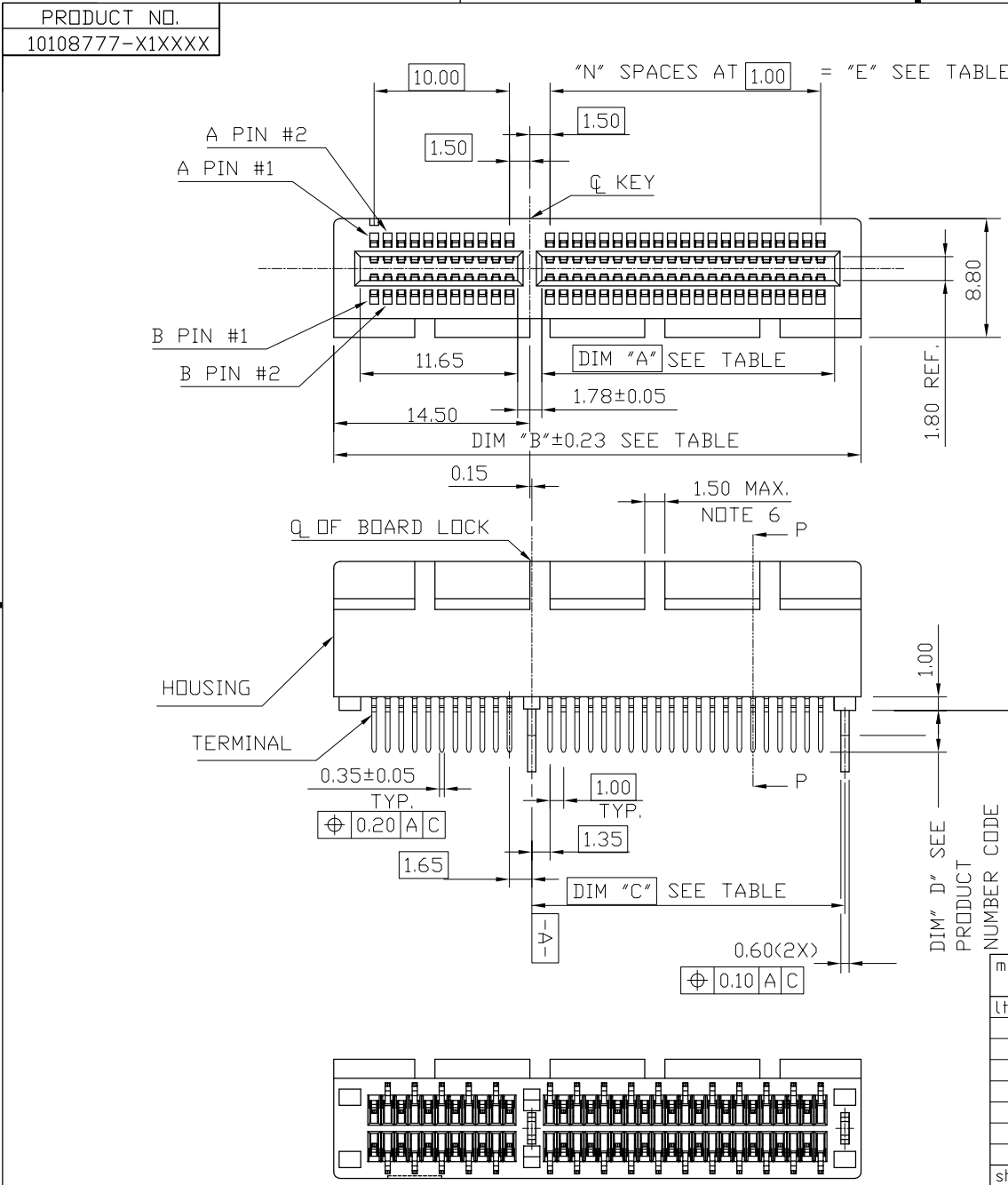
A

A

B

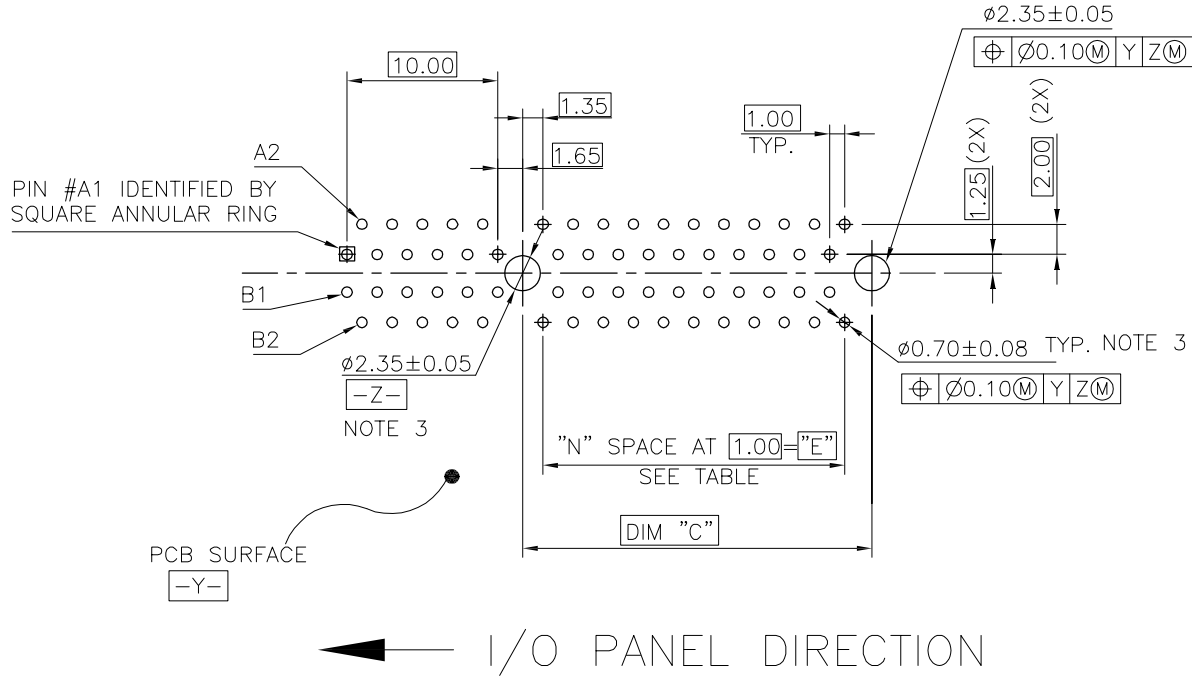
B

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								dwg no	
								sheet 2 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		H					



METAL BOARD LOCKS

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5		⊕		PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								dwg no	
								sheet 3 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		H					



RECOMMENDED FOOTPRINT

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								sheet 4 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		H					

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-0 RATED.
TERMINAL: COPPER ALLOY.

PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE
SOLDER TAIL: TIN OR TIN /LEAD(90/10)- SEE PRODUCT NUMBER CODE 100u" MIN. OVER 50u" NICKEL.

METAL BOARD LOCKS: COPPER ALLOY.
FINISH: 100u" TIN OR TIN/LEAD(90/10) OVER 50u" NICKEL
UNDERPLATE SEE PRODUCT NUMBER CODE.

2.PRODUCT SPECIFICATION: GS-12-233.

③THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.
THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM Z.

④NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F".

⑤CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

⑥FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS:

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY:

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C TEMPERATURE FOR 10 SECONDS IN RE-FLOW APPLICATION, SEE NOTE 8 FOR APPLICATION.

PRODUCT NUMBER CODE

10108777 -X X X X X X □ □

HOUSING COLOR OPTIONS

- 0-NATURAL
- 1-BLACK

PEGS OPTIONS

- 0-PLASTIC PEGS, DIM
- 1-METAL BOARD LOCKS
- 2-SINGLE PLASTIC PEGS

TERMINAL PLATING OPTIONS

- 0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 3-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS
- 4-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS
- 5-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN/LEAD TAIL AREA ---INCOMPLIANT RoHS

LEAD FREE OPTION

LEAVE BLANK FOR TERMINAL PLATING 3.4.5
"LF" FOR TERMINAL PLATING OPTION 0,1,2

POS OPTIONS

- 0-36
- 1-64
- 2-98
- 3-164

TAIL LENGTH OPTIONS

	DIM "D"	PCB THICKNESS	DIM "G"
0	2.30 ^{+0.25} / _{-0.13}	1.56±0.10	1.70±0.15
1	3.10 ^{+0.25} / _{-0.13}	2.36±0.10	2.50±0.15
2	2.54±0.25	1.56±0.10	1.70±0.15
3	1.90±0.25	1.56±0.10	1.70±0.15
4	3.10 ^{+0.25} / _{-0.13}	2.0±0.10	1.70±0.15

CONNECTOR	# POS REF.	N	DIM "A"	DIM "B"	DIM "C"	"E"
1 PORT	36	6	7.65	25.00	9.15	6.00
4 PORT	64	20	21.65	39.00	23.15	20.00
8 PORT	98	37	38.65	56.00	40.15	37.00
16 PORT	164	70	71.65	89.00	73.15	70.00

8.AN ADEQUATE PROCEDURE SET FORTH IN THE FOLLOWING ENSURE THAT THE PRODUCT RELIABILITY CAN BE ACHIEVED DURING AND AFTER PCB ASSEMBLY OPERATION.

8.1IF PARTIAL LOT ARE USED, THE REMAINING CONNECTORS MUST BE RESEALED AND PLACED IN SAFE STORAGE WITHIN SIX HOURS OF BAG OPENING.

8.2THE SAFE STORAGE CONDITION IS RECOMMENDED AT 25°C, 40%RH.

8.3NOT FOLLOWING THE PROCEDURE MAY CAUSE BLISTER DAMAGE DURING RE-FLOW PROCESS.

8.4IF BAKING IS REQUIRED, CONNECTOR SHALL BE BAKED FOR 4 HOURS AT 125°C.

8.5REFERENCE SPECIFICATION: IPC/JEDEC J-STD-033A.

PACKAGING OPTIONS

E-HARD TRAY WITH MYLAR FOR VACUUM PACKAGING (FOR 164P ONLY)

T-SOFT TRAY PACKAGING

C-SOFT TRAY PACKAGING WITH 10MM CAP

M-SOFT TRAY PACKAGING & MYLAR TAPE. SEE FIGURE 1

Y-HARD TRAY PACKAGING (FOR 36P,98P AND 164P ONLY)

Z-HARD TRAY PACKAGING WITH MYLAR (FOR 36P,98P AND 164P ONLY)

H-SMALLER HARD TRAY PACKAGING WITH 30MM CAP (323X136X17.7 FOR 164P ONLY)

△ Q-SMALLER HARD TRAY PACKAGING (323X136X17.7 FOR 164P ONLY)

R-TAPE & REEL PACKAGING WITHOUT MYLAR

(FOR 34, 64, 98P ONLY)

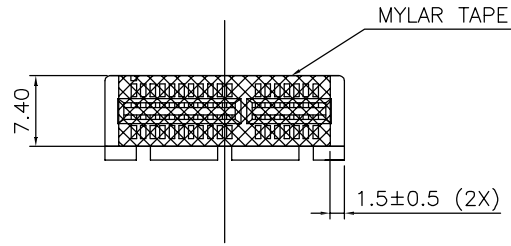
W-TAPE & REEL PACKAGING WITHOUT MYLAR

(FOR 98P ONLY), WITH 18.0MM CAVITY WIDTH

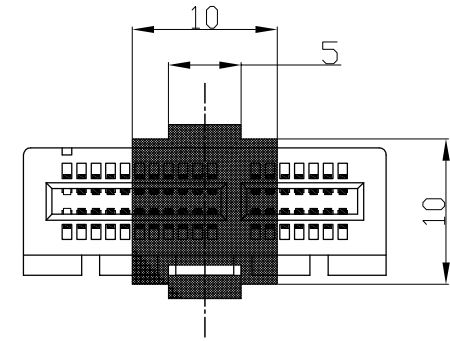
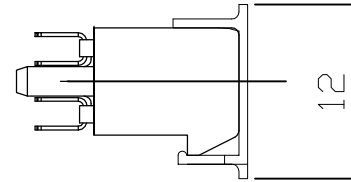
A-TAPE & REEL PACKAGING WITH MYLAR

(FOR 36, 64, 98P ONLY)

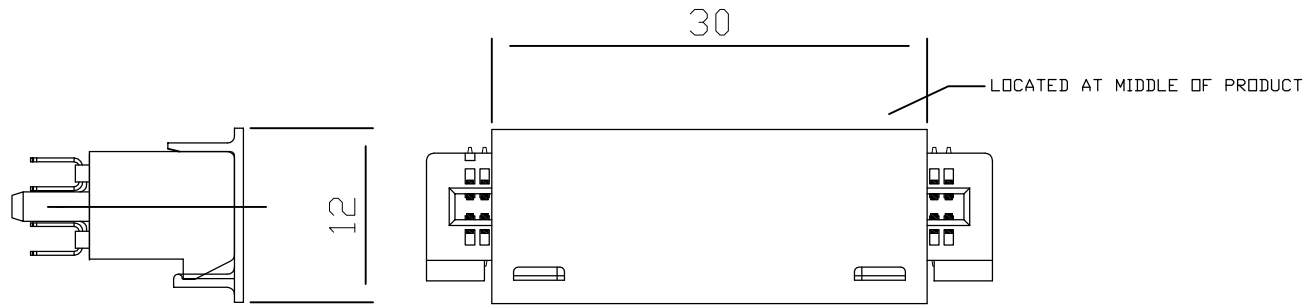
mat'l. code		-		surface		- ✓ tolerance		ASME_Y14.5		projection		product family		PCI_EXPRESS	
lfr		ecn no		dr		date		tolerances unless otherwise specified		MM		title		PCI_EXPRESS_CARD_EDGE_GEN3	
								angles		MM		TH_ASS'Y		5	
								±2'		scale N/A		dwg no		sheet 6 of 7 size	
				dr		ZHENHUA_LIU		2016-03-30		Amphenol FCI		10108777		A4	
				enfr		ZHENHUA_LIU		2016-03-30				type		CUSTOMER Drawing	
				chr		STONE_LI		2016-03-30							
				appd		PM_ZHENG		2016-03-30							
sheet index		revision		H											



POSTION OF MYLAR



POSTION OF CAP <10x10>



POSTION OF 30MM CAP<30X12>

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
				angles				TH_ASS'Y	
				±2'				scale N/A	
		dr		ZHENHUA_LIU		2016-03-30		dwg no	
		enfr		ZHENHUA_LIU		2016-03-30		sheet 7 of 7	
		chr		STONE_LI		2016-03-30		size	
		appd		PM_ZHENG		2016-03-30		A4	
								10108777	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		H					

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9